| FORM PTO-1449 (REV. 7-80) | | | 9 | U.S. DEPARTMENT OF COMMERCE ATTY, DOCKET NO. PATENT AND TRADEMARK OFFICE H-957-04 | | | SERIAL NO. | | | | |
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| LIST OF DOCUMENTS CITED B (Use several sheets if nece | | | | | | | GROUP | | | | |
| | | | | September 25, 2003 | | | | | | | |
| U.S. PATENT DOCUMENTS | | | | | | | | | | | |
| * EXAMINER INITIAL | | | DOCUMENT | DATE | | NAME | CLASS | SUBCLASS | FILING DA | | |
| PU | | AA | 5,026,669 | 06/25/91 | Shinohara | | 1 | , | | | |
| | | АВ | 5,327,104 | 07/05/94 | Kikushima | | | | | | |
| | | AC | 5,731,231 | 03/24/98 | Miyajima | | | | | | |
| | | AD | 5,973,395 | 10/26/99 | Suzuki et al | | | | | | |
| | . | AE | 6,208,020 | 03/27/01 | Minamio et al | | / | | | | |
| <u></u> | | AF | 6,399,423 | 06/2002 | Matsuura et a | 1 | | | | | |
| *N | | AG | 6,208,020 | 03/2001 | Minamio et al | | | | | | |
| | | AH | | | | | | | | | |
| | | ΑI | <u> </u> | | | | | | | | |
| | | AJ | | | | | | | | | |
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| FOREIGN PATENT DOCUMENTS | | | | | | | | | | | |
| \ | | | DOCUMENT | DATE | C | COUNTRY | CLASS | SUBCLASS | TRANSLAT YES I | TIO NO | |
| DN | | AL | 11-195743 | 07/21/99 | Japan | | | | | | |
| PN AM 2 | | 2-240940 | 09/25/90 | Japan | | | | | | | |
| | AN | | | | | | | | | | |
| | AO | | | | | | | | | | |
| | | AP | | | | | | | | | |
| OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.) | | | | | | | | | | | |
| Pr | | A.B. | "Semiconductor Assembling/Testing Technique of '99", Extra Issue of Monthly | | | | | | | | |
| | / | AR | Semicor | iductor Wor | ld, July 27, 1 | 998. | | | | | |
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| * EXAMINER: Initial if reference considered, whether or not distion is in conformance with MPEP 609; Draw line through distion if not in conformance and not considered. Include copy of this form next communication to applicant. | | | | | | | | | | | |